WHAT IS CLAIMED IS:

1. A semiconductor device comprising:

a semiconductor substrate on which a photoelectric converting portion is formed;

a package which comprises at least a light-shading means for shading an incoming light to said photoelectric converting portion, wherein

said light-shading means is formed at an area corresponding to at least the photoelectric converting portion, said area being on the side of the rear surface of the semiconductor substrate.

2. A semiconductor device according to claim 1, wherein said package comprises a wiring board with a connecting terminal formed on the rear surface.

3. A semiconductor device according to claim 1 or 2, wherein said light shading means is rough surface area.

4. A semiconductor device according to claim 1 or 2, wherein said light shading means is a multi-layer film composed of films with different refraction indices formed on the area corresponding to the photoelectric converting portion on the rear surface of said semiconductor substrate.

5. A semiconductor device according to claim 1 or 2, wherein said light shading means is a light-shading film formed on the rear surface of said semiconductor substrate.

6. A semiconductor device according to claim 1 or 2, wherein said wiring board is connected to said semiconductor substrate through a light-shading resin material.

7. A semiconductor device according to claim 1 or 2,

wherein a surface of said wiring board is rough surface.

8. A semiconductor device according to claims 1 or 2, wherein said wiring board includes a light shading layer in the interior or on the rear surface.

9. A method for manufacturing a semiconductor device comprising the steps of:

a forming step for forming a plurality of semiconductor devices on the front surface of a semiconductor substrate;

a bonding step for bonding a wiring board on the rear surface of said semiconductor substrate;

a separating step for separating a bonding structure obtained by bonding into semiconductor devices, and

a grinding step for forming rough surface on the rear surface of the semiconductor substrate.

10. A method for manufacturing a semiconductor device comprising the steps of:

a forming step for forming a plurality of semiconductor devices on the front surface of a semiconductor substrate;

a bonding step for bonding a wiring board on the rear surface of said semiconductor substrate through light-shading adhesive; and a separating step for separating a bonding structure obtained by bonding into semiconductor devices.